

X9421 Low Noise/Low Power/SPI Bus

January 14, 2009

FN8196.4

Single Digitally Controlled (XDCP™) Potentiometer

Description

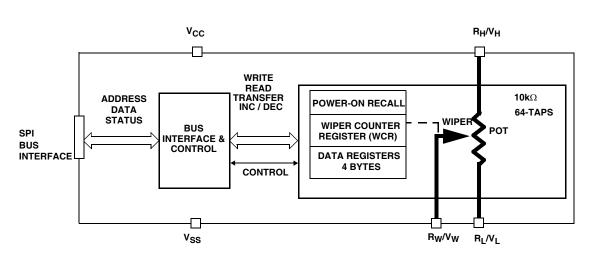
The X9421 integrates a single digitally controlled potentiometer (XDCP) on a monolithic CMOS integrated circuit.

The digital controlled potentiometer is implemented using 63 resistive elements in a series array. Between each element are tap points connected to the wiper terminal through switches. The position of the wiper on the array is controlled by the user through the SPI bus interface. The potentiometer has associated with it a volatile Wiper Counter Register (WCR) and a four non-volatile Data Registers that can be directly written to and read by the user. The contents of the WCR controls the position of the wiper on the resistor array though the switches. Power-up recalls the contents of the default data register (DR0) to the WCR.

The XDCP can be used as a three-terminal potentiometer or as a two terminal variable resistor in a wide variety of applications including control, parameter adjustments, and signal processing.

Features

- Single Voltage Potentiometer
- 64 Resistor Taps
- SPI Serial Interface for Write, Read, and Transfer Operations of the Potentiometer
- Wiper Resistance, 150Ω Typical at 5V
- 4 Non-Volatile Data Registers
- Non-Volatile Storage of Multiple Wiper Positions
- Power-on Recall. Loads Saved Wiper Position on Power-up.
- Standby Current < 5µA Max
- V_{CC}: 2.7V to 5.5V Operation
- 2.5k Ω , 10k Ω End to End Resistance
- 100 yr. Data Retention
- Endurance: 100, 000 Data Changes per Bit per Register
- 14 Ld TSSOP, 16 Ld SOIC
- Low Power CMOS
- Pb-Free Available (RoHS Compliant)



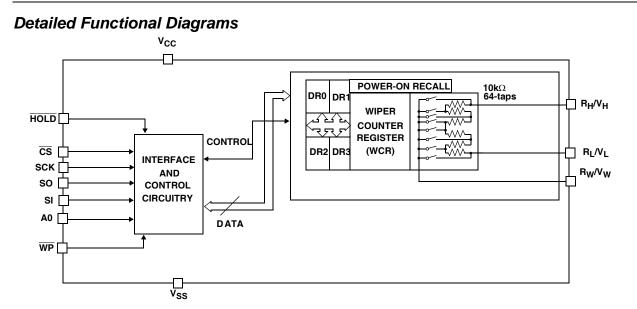
Block Diagram

Ordering Information

PART NUMBER	PART MARKING	V _{CC} LIMITS (V)	POTENTIOMETER ORGANIZATION (kΩ)	TEMP RANGE (°C)	PACKAGE
X9421YS16*	X9421YS	5 ±10%	2.5	0 to +70	16 Ld SOIC (300 mil)
X9421YS16Z* (Note)	X9421YS Z	_		0 to +70	16 Ld SOIC (300 mil) (Pb-Free)
X9421YS16I*	X9421YS I	_		-40 to +85	16 Ld SOIC (300 mil)
X9421YS16IZ* (Note)	X9421YS ZI	_		-40 to +85	16 Ld SOIC (300 mil) (Pb-Free)
X9421YV14*	X9421 YV	_		0 to +70	14 Ld TSSOP (4.4mm)
X9421YV14Z* (Note)	X9421 YVZ	_		0 to +70	14 Ld TSSOP (4.4mm) (Pb-Free)
X9421YV14I*	X9421 YV I	_		-40 to +85	14 Ld TSSOP (4.4mm)
X9421YV14IZ* (Note)	X9421 YVZI	_		-40 to +85	14 Ld TSSOP (4.4mm) (Pb-Free)
X9421WS16*	X9421WS	_	10	0 to +70	16 Ld SOIC (300 mil)
X9421WS16Z* (Note)	X9421WS Z	_		0 to +70	16 Ld SOIC (300 mil) (Pb-Free)
X9421WS16I*	X9421WS I	_		-40 to +85	16 Ld SOIC (300 mil)
X9421WS16IZ* (Note)	X9421WS ZI	_		-40 to +85	16 Ld SOIC (300 mil) (Pb-Free)
X9421WV14*	X9421 WV	_		0 to +70	14 Ld TSSOP (4.4mm)
X9421WV14Z* (Note)	X9421 WV Z	_		0 to +70	14 Ld TSSOP (4.4mm) (Pb-Free)
X9421WV14I*	X9421 WV I	_		-40 to +85	14 Ld TSSOP (4.4mm)
X9421WV14IZ* (Note)	X9421 WVZI	_		-40 to +85	14 Ld TSSOP (4.4mm) (Pb-Free)
X9421YS16-2.7*	X9421YS F	2.7 to 5.5	2.5	0 to +70	16 Ld SOIC (300 mil)
X9421YS16Z-2.7* (Note)	X9421YS ZF	_		0 to +70	16 Ld SOIC (300 mil) (Pb-Free)
X9421YS16I-2.7*	X9421 YS G	_		-40 to +85	16 Ld SOIC (300 mil)
X9421YS16IZ-2.7* (Note)	X9421 YS ZG	_		-40 to +85	16 Ld SOIC (300 mil) (Pb-Free)
X9421YV14-2.7*	X9421 YVF	_		0 to +70	14 Ld TSSOP (4.4mm)
X9421YV14Z-2.7* (Pb-free)	X9421 YVZF	_		0 to +70	14 Ld TSSOP (4.4mm) (Pb-Free)
X9421YV14I-2.7*	X9421 YVG	_		-40 to +85	14 Ld TSSOP (4.4mm)
X9421YV14IZ-2.7* (Pb-free)	X9421 YVZG	_		-40 to +85	14 Ld TSSOP (4.4mm) (Pb-Free)
X9421WS16-2.7*	X9421WS F	_	10	0 to +70	16 Ld SOIC (300 mil)
X9421WS16Z-2.7* (Note)	X9421WS ZF	_		0 to +70	16 Ld SOIC (300 mil) (Pb-Free)
X9421WS16I-2.7*	X9421WS G	_		-40 to +85	16 Ld SOIC (300 mil)
X9421WS16IZ-2.7* (Note)	X9421WS ZG	_		-40 to +85	16 Ld SOIC (300 mil) (Pb-Free)
X9421WV14-2.7*	X9421 WVF	1		0 to +70	14 Ld TSSOP (4.4mm)
X9421WV14Z-2.7* (Pb-free)	X9421 WVZF	1		0 to +70	14 Ld TSSOP (4.4mm) (Pb-Free)
X9421WV14I-2.7*	X9421 WVG	-		-40 to +85	14 Ld TSSOP (4.4mm)
X9421WV14IZ-2.7* (Pb-free)	X9421 WVZG	1		-40 to +85	14 Ld TSSOP (4.4mm) (Pb-Free)

*Add "T1" suffix for tape and reel. Please refer to TB347 for details on reel specifications.

NOTE: These Intersil Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020

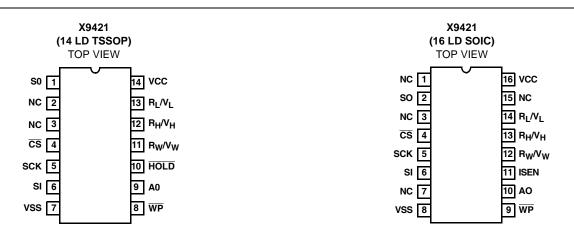


Circuit Level Applications

- Vary the Gain of a Voltage Amplifier
- Provide Programmable DC Reference Voltages for Comparators and Detectors
- Control the Volume in Audio Circuits
- Trim Out the Offset Voltage Error in a Voltage Amplifier Circuit
- Set the Output Voltage of a Voltage Regulator
- Trim the Resistance in Wheatstone Bridge Circuits
- Control the Gain, Characteristic Frequency and Q-factor in Filter Circuits
- Set the Scale Factor and Zero Point in Sensor Signal Conditioning Circuits
- Vary the Frequency and Duty Cycle of Timer ICs
- Vary the DC Biasing of a Pin Diode Attenuator in RF Circuits
- Provide a Control Variable (I, V, or R) in Feedback Circuits

System Level Applications

- · Adjust the contrast in LCD displays
- Control the Power Level of LED Transmitters in Communication Systems
- Set and Regulate the DC Biasing Point in an RF Power Amplifier in Wireless Systems
- Control the Gain in Audio and Home Entertainment Systems
- Provide the Variable DC Bias for Tuners in RF Wireless Systems
- Set the Operating Points in Temperature Control Systems
- Control the Operating Point for Sensors in Industrial Systems
- Trim Offset and Gain Errors in Artificial Intelligent Systems



Pin Assignments

TSSOP PIN NO.	SOIC PIN NO.	SYMBOL	DESCRIPTION
1	2	SO	Serial Data Output
2, 3	3, 1, 7, 5	NC	No Connect
4	4	CS	Chip Select
5	5	SCK	Serial Clock
6	6	SI	Serial Data Input
7	8	VSS	System Ground
8	9	WP	Hardware Write Protect
9	10	A0	Device Address
10		HOLD	Device select. Pause the serial bus.
11	12	R _W /V _W	Wiper Terminal of the Potentiometer.
12	13	R _H /V _H	High Terminal of the Potentiometer.
13	14	R _L /V _L	Low Terminal of the Potentiometer.
14	16	VCC	System Supply Voltage

Pin Descriptions

Host Interface Pins

SERIAL OUTPUT (SO)

SO is a push/pull serial data output pin. During a read cycle, data is shifted out on this pin. Data is clocked out by the falling edge of the serial clock.

SERIAL INPUT

SI is the serial data input pin. All opcodes, byte addresses and data to be written to the potentiometer and pot register are input on this pin. Data is latched by the rising edge of the serial clock.

SERIAL CLOCK (SCK)

The SCK input is used to clock data into and out of the X9421.

CHIP SELECT (CS)

When \overline{CS} is HIGH, the X9421 is deselected and the SO pin is at high impedance, and (unless an internal write cycle is underway) the device will be in the standby state. \overline{CS} LOW enables the X9421, placing it in the active power mode. It should be noted that after a power-up, a HIGH to LOW transition on \overline{CS} is required prior to the start of any operation.

HOLD (HOLD)

HOLD is used in conjunction with the $\overline{\text{CS}}$ pin to select the device. Once the part is selected and a serial sequence is underway, HOLD may be used to pause the serial communication with the controller without resetting the serial sequence. To pause, HOLD must be brought LOW while SCK is LOW. To resume communication, HOLD is brought HIGH, again while SCK is LOW. If the pause feature is not used, HOLD should be held HIGH at all times.

DEVICE ADDRESS (A₀)

The address input is used to set the least significant bit of the 8-bit slave address. A match in the slave address serial data stream must be made with the address input in order to initiate communication with the X9421. A maximum of two devices may occupy the SPI serial bus.

Potentiometer Pins

V_H/R_H , V_L/R_L

The V_H/R_H and V_L/R_L inputs are equivalent to the terminal connections on either end of a mechanical potentiometer.

V_W/R_W

The wiper output is equivalent to the wiper output of a mechanical potentiometer.

HARDWARE WRITE PROTECT INPUT (WP)

The $\overline{\text{WP}}$ pin when LOW prevents nonvolatile writes to the Data Registers. Writing to the Wiper Counter Register is not restricted.

SYSTEM/DIGITAL SUPPLY (V_{CC})

VCC is the supply voltage for the system/digital section. VSS is the system ground.

Principles of Operation

The X9421 is a highly integrated microcircuit incorporating a resistor array and associated registers and counter and the serial interface logic providing direct communication between the host and the XDCP potentiometer.

Serial Interface

The X9421 supports the SPI interface hardware conventions. The device is accessed via the SI input with data clocked in on the rising SCK. $\overline{\text{CS}}$ must be LOW and the HOLD and WP pins must be HIGH during the entire operation.

The SO and SI pins can be connected together, since they have three state outputs. This can help to reduce system pin count.

Array Description

The X9421 is comprised of one resistor array containing 63 discrete resistive segments that are connected in series. The physical ends of each array are equivalent to the fixed terminals of a mechanical potentiometer (V_H/R_H and V_L/R_L inputs).

At both ends of the array and between each resistor segment is a CMOS switch connected to the wiper (V_W/R_W) output. Within the individual array only one switch may be turned on at a time.

These switches are controlled by a Wiper Counter Register (WCR). The six bits of the WCR are decoded to select, and

enable, one of sixty-four switches. The block diagram of the potentiometer is shown in Figure 1.

Wiper Counter Register (WCR)

The X9421 contains a Wiper Counter Register. The WCR can be envisioned as a 6-bit parallel and serial load counter with its outputs decoded to select one of sixty-four switches along its resistor array. The contents of the WCR can be altered in four ways: it may be written directly by the host via the Write Wiper Counter Register instruction (serial load); it may be written indirectly by transferring the contents of one of four associated Data Registers via the XFR Data Register instruction (parallel load); it can be modified one step at a time by the Increment/Decrement instruction. Finally, it is loaded with the contents of its data register zero (DR0) upon power-up.

The Wiper Counter Register is a volatile register; that is, its contents are lost when the X9421 is powered-down. Although the register is automatically loaded with the value in DR0 upon power-up, this may be different from the value present at power-down.

Data Registers

The potentiometer has four 6-bit nonvolatile Data Registers. These can be read or written directly by the host. Data can also be transferred between any of the four Data Registers and the WCR. It should be noted all operations changing data in one of the Data Registers is a nonvolatile operation and will take a maximum of 10ms.

If the application does not require storage of multiple settings for the potentiometer, the Data Registers can be used as regular memory locations for system parameters or user preference data.

Register Descriptions

TABLE 1. DATA REGISTERS, (6-BIT), NONVOLATILE

0	0	D5	D4	D3	D2	D1	D0
(MS	SB)					(LS	SB)

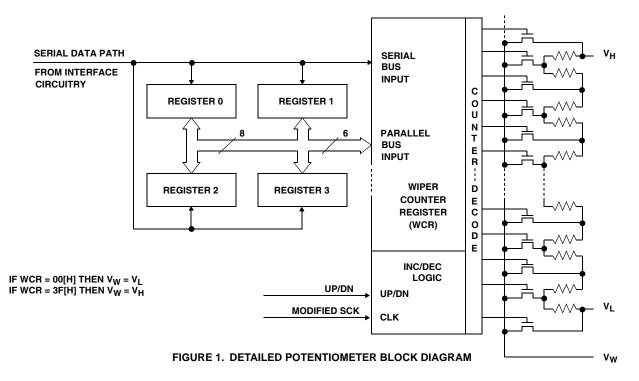
There are four 6-bit Data Registers associated with the potentiometer.

 {D5~D0}: These bits are for general purpose Nonvolatile data storage or for storage of up to four different wiper values.

TABLE 2. WIPER COUNTER REGISTER, (6-BIT), VOLATILE

0	0	WP5	WP4	WP3	WP2	WP1	WP0
(MS	SB)					(LS	SB)

• {WP5~WP0}: These bits specify the wiper position of the potentiometer.



Write In Process

The contents of the Data Registers are saved to nonvolatile memory when the $\overline{\text{CS}}$ pin goes from LOW to HIGH after a complete write sequence is received by the device. The progress of this internal write operation can be monitored by a Write In Process bit (WIP). The WIP bit is read with a Read Status command.

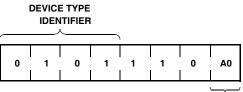
Instructions

Address/Identification (ID) Byte

The first byte sent to the X9421 from the host, following a \overline{CS} going HIGH to LOW, is called the Address or Identification byte. The most significant four bits of the slave address are a device type identifier, for the X9421 this is fixed as 0101[B] (refer to Figure 2).

The least significant bit in the ID byte selects one of two devices on the bus. The physical device address is defined by the state of the A₀ input pin. The X9421 compares the serial data stream with the address input state; a successful compare of the address bit is required for the X9421 to successfully continue the command sequence. The A₀ input can be actively driven by a CMOS input signal or tied to V_{CC} or V_{SS}.

The remaining three bits in the ID byte must be set to 110.



DEVICE ADDRESS

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FIGURE 2. ADDRESS/IDENTIFICATION BYTE FORMAT
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Instruction Byte

The next byte sent to the X9421 contains the instruction and register pointer information. The four most significant bits are the instruction. The next two bits point to one of four Data Registers. The format is shown below in Figure 3.

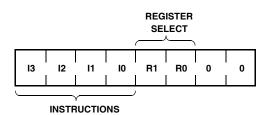


FIGURE 3. INSTRUCTION BYTE FORMAT

The four high order bits of the instruction byte specify the operation. The next two bits (R_1 and R_0) select one of the four registers that is to be acted upon when a register oriented instruction is issued. The last two bits are defined as 0.

Two of the eight instructions are two bytes in length and end with the transmission of the instruction byte. These instructions are:

- <u>XFR Data Register to Wiper Counter Register</u>—This instruction transfers the contents of one specified Data Register to the Wiper Counter Register.
- <u>XFR Wiper Counter Register to Data Register</u>—This instruction transfers the contents of the Wiper Counter Register to the specified associated Data Register.

The basic sequence of the two byte instructions is illustrated in Figure 4. These two-byte instructions exchange data between the WCR and one of the Data Registers. A transfer from a Data Register to a WCR is essentially a write to a static RAM, with the static RAM controlling the wiper position. The response of the wiper to this action will be delayed by t_{WRL} . A transfer from the WCR (current wiper position), to a Data Register is a write to nonvolatile memory and takes a minimum of t_{WR} to complete. The transfer can occur between the potentiometer and one of its associated registers.

Five instructions require a three-byte sequence to complete. These instructions transfer data between the host and the X9421; either between the host and one of the Data Registers or directly between the host and the WCR. These instructions are:

- <u>Read Wiper Counter Register</u>—read the current wiper position of the pot,
- <u>Write Wiper Counter Register</u>—change current wiper position of the pot,
- <u>Read Data Register</u>—read the contents of the selected data register;
- <u>Write Data Register</u>—write a new value to the selected data register.
- <u>Read Status</u>—This command returns the contents of the WIP bit which indicates if the internal write cycle is in progress.

The sequence of these operations is shown in Figure 5 and Figure 6.

The final command is Increment/Decrement. It is different from the other commands, because it's length is indeterminate. Once the command is issued, the master can clock the wiper up and/or down in one resistor segment step; thereby, providing a fine tuning capability to the host. For each SCK clock pulse (t_{HIGH}) while SI is HIGH, the selected wiper will move one resistor segment towards the V_H/R_H terminal. Similarly, for each SCK clock pulse while SI is LOW, the selected wiper will move one resistor segment towards the V_L/R_L terminal. A detailed illustration of the sequence and timing for this operation are shown in Figure 7 and 8.

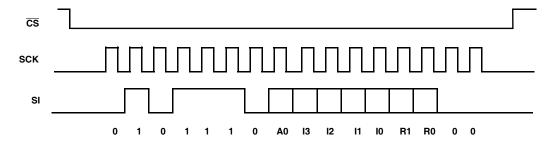


FIGURE 4. TWO-BYTE INSTRUCTION SEQUENCE

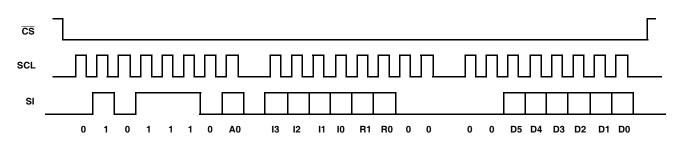
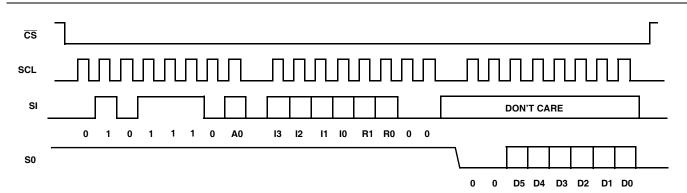


FIGURE 5. THREE-BYTE INSTRUCTION SEQUENCE (WRITE)

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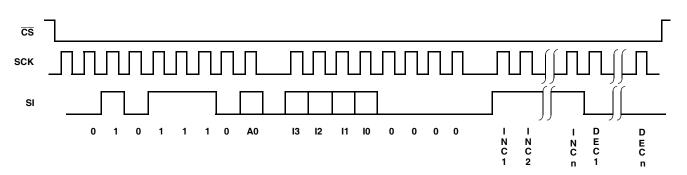


FIGURE 7. INCREMENT/DECREMENT INSTRUCTION SEQUENCE

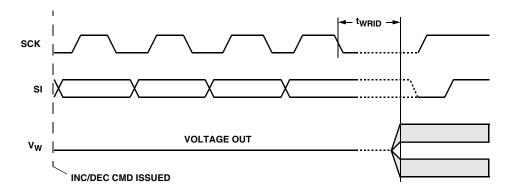


FIGURE 8. INCREMENT/DECREMENT TIMING LIMITS

				1	TABLE	3. INS	STRUC	TION	SET
			IN	STRU	CTION	I SET			
INSTRUCTION	l ₃	l ₂	I ₁	I ₀	R ₁	R ₀			OPERATION
Read Wiper Counter Register	1	0	0	1	0	0	0	0	Read the contents of the Wiper Counter Register
Write Wiper Counter Register	1	0	1	0	0	0	0	0	Write new value to the Wiper Counter Register
Read Data Register	1	0	1	1	1/0	1/0	0	0	Read the contents of the Data Register pointed to by $R_1 - R_0$
Write Data Register	1	1	0	0	1/0	1/0	0	0	Write new value to the Data Register pointed to by $R_1 - R_0$
XFR Data Register to Wiper Counter Register	1	1	0	1	1/0	1/0	0	0	Transfer the contents of the Data Register pointed to by ${\sf R}_1$ - ${\sf R}_0$ to the Wiper Counter Register
XFR Wiper Counter Register to Data Register	1	1	1	0	1/0	1/0	0	0	Transfer the contents of the Wiper Counter Register to the Data Register pointed to by $R_1 - R_0$
Increment/Decrement Wiper Counter Register	0	0	1	0	0	0	0	0	Enable Increment/decrement of the Wiper Counter Register
Read Status (WIP bit)	0	1	0	1	0	0	0	1	Read the status of the internal write cycle, by checking the WIP bit.

Instruction Format

NOTES:

- 1. "A0": stands for the device addresses sent by the master.
- 2. WPx refers to wiper position data in the Wiper Counter Register "I": stands for the increment operation, SI held HIGH during active SCK phase (high).
- 3. "D": stands for the decrement operation, SI held LOW during active SCK phase (high).

Read Wiper Counter Register (WCR)

	ID	ΤY	/ICE PE FIFIE	_	A		EVIC RES	E SES											(S		R POSI (X9421	-)		CS RISING
EDGE	0	1	0	1	1	1	0	A0	1	0	0	1	0	0	0	0	0	0	WP5	WP4	WP3	WP2	WP1	WP0	EDGE

Write Wiper Counter Register (WCR)

	DEVICE TYPE IDENTIFIER	DEVICE ADDRESSES	INSTRUCTION OPCODE		DATA BYTE (SENT BY HOST ON SI)	
EDGE	0 1 0 1	1 1 0 A0	1 0 1 0	0 0 0 0	0 0 WP5 WP4 WP3 WP2 WP1 WP0	EDGE

Read Data Register (DR)

Read the contents of the Register pointed to by R1 - R0.

		ΤY	/ICE 'PE TIFIE		AI			E SES			JCTI ODE			EGIS [.]					(SE		TA BYT ′ X9421	_	D)		CS RISING
EDGE	0	1	0	1	1	1	0	A0	1	0	1	1	R1	R0	0	0	0	0	WP5	WP4	WP3	WP2	WP1	WP0	EDGE

Write Data Register (DR)

Write a new value to the Register pointed to by R1 - R0.

cs		ΤY	/ICE PE TIFII				ICE ESS			STRL OPC	-	-		EGI DRI	-	RES			(SEI		ta by Y hos	'TE ST ON	SI)		cs	
FALLING EDGE	0	1	0	1	1	1	0	A 0	1	1	0	0	R 1	R 0	0	0	0	0	WP 5	WP 4	WP 3	WP 2	WP 1	WP 0	RISING EDGE	HIGH-VOLTAGE WRITE CYCLE

Transfer Data Register (DR) to Wiper Counter Register (WCR)

Transfer the contents of the Register pointed to by R1 - R0 to the WCR.

		ΤY	/ICE PE TIFIE	_	A		VIC	E SES			JCTI ODE			EGIS [.] DRE			CS RISING
EDGE	0	1	0	1	1	1	0	A0	1	1	0	1	R1	R0	0	0	EDGE

Transfer Wiper Counter Register (WCR) to Data Register (DR)

	10	Т	VICE 'PE TIFIE	-	AI		VIC	E SES			JCTI ODE			EGIS		-	CS RISING	HIGH-VOLTAGE
G EDGE	0	1	0	1	1	1	0	A0	1	1	1	0	R1	R0	0	0	EDGE	WRITE CYCLE

Increment/Decrement Wiper Counter Register (WCR)

			E TY TIFIE		Α		VIC	E SES		STRU OPC									 			MENT N SD/		CS RISING
EDGE	0	1	0	1	1	1	0	A0	0	0	1	0	0	0	0	0	I/D	I/D		•	•	I/D	I/D	EDGE

Read Status

cs		ТΥ	/ICE Pe Tifie		A			E SES		STRI OPC	-	-					(SEN	D/ IT B		BY ⁻ 9421		I SC))	cs
FALLING EDGE	0	1	0	1	1	1	0	A0	0	1	0	1	0	0	0	1	0	0	0	0	0	0	0	W IP	

Absolute Maximum Ratings

Supply Voltage (V _{CC} Limits)
X9421 5V ±10%
X9421-2.72.7V to 5.5V
Voltage on SCK, SDA any address input
with respect to V _{SS} :
$\Delta V = (V_{H} - V_{L}) \dots \dots$
I _W (10s)
Any VH/RH, VL/RL, VW/RW VSS to VCC

Thermal Information

Thermal Resistance (Typical, Note 1)	θ _{JA} (°C/W)
14 Lead TSSOP	92
16 Lead SOIC	82
Temperature Under Bias65°	°C to +135°C
Storage Temperature65°	°C to +150°C
Pb-Free Reflow Profilese	ee link below
http://www.intersil.com/pbfree/Pb-FreeReflow.asp	

Operating Conditions

Temperature Range	
Commercial 0°C to +7	70°C
Industrial40°C to +8	35°C

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

NOTES:

1. θ_{JA} is measured with the component mounted on a low effective thermal conductivity test board in free air. See Tech Brief TB379 for details

			LIMITS						
SYMBOL	PARAMETER	TEST CONDITIONS	MIN. (Note 5)	TYP. (Note 6)	MAX. (Note 5)	UNITS			
Rtotal	End to End Resistance Tolerance		-20		+20	%			
	Power Rating	+25°C, each pot			50	mW			
R _W	Wiper Resistance	Wiper Current lw = $(V_H - V_L)/R_{TOTAL}, V_{CC} = 5V$		150	250	Ω			
		Wiper Current $Iw = (V_H - V_L)/R_{TOTAL}, V_{CC} = 3V$		400	1000	Ω			
V _{TERM}	Voltage on any V_H/R_H , V_L/R_L , V_W/R_W	V _{SS} = 0V	V _{SS}		V _{CC}	V			
	Noise	Ref: 1kHz		-120		dBV			
	Resolution (Note 4)	(Note 5)		1.6		%			
	Absolute Linearity (Note 1)	Vw(n)(actual) - Vw(n)(expected)	-1		+1	MI (Note 3)			
	Relative Linearity (Note 2)	V _{w(n + 1)} - [V _{w(n) + MI}]	-0.2		+0.2	MI (Note 3)			
	Temperature Coefficient of R _{TOTAL}	(Note 5)		±300		ppm/°C			
	Ratio metric Temperature Coefficient	(Note 5)		±20		ppm/°C			
C _H /C _L /C _W	Potentiometer Capacitances	See "Circuit #3 SPICE Macro Model" on page 13		10/10/25		pF			
I _{AL}	Rh, RI, Rw leakage current	VIN = VSS to VCC. Device is in stand-by mode.		0.1	10	μΑ			

Analog Specifications (Over recommended operating conditions unless otherwise stated.)

				LIM	IITS	
SYMBOL	PARAMETER	TEST CONDITIONS	MIN (Note 5)	TYP (Note 6)	MAX (Note 5)	UNITS
I _{CC1}	V _{CC} Supply Current (Active)	$f_{SCK} = 2MHz$, SO = Open, Other Inputs = V_{SS}			400	μA
I _{CC2}	V _{CC} Supply Current (Nonvolatile Write)	$f_{SCK} = 2MHz$, SO = Open, Other Inputs = V_{SS}			3.5	mA
I _{SB}	V _{CC} Current (Standby)	$SCK = SI = V_{SS}$, Addr. = V_{SS}			3	μA
ILI	Input Leakage Current	$V_{IN} = V_{SS}$ to V_{CC}			10	μA
I _{LO}	Output Leakage Current	$V_{OUT} = V_{SS}$ to V_{CC}			10	μA
VIH	Input HIGH Voltage		V _{CC} x 0.7		V _{CC} + 0.3	V
V _{IL}	Input LOW Voltage		-0.5		V _{CC} x 0.1	V
V _{OL}	Output LOW Voltage	I _{OL} = 3mA			0.4	V

DC Electrical Specifications (Over the recommended operating conditions unless otherwise specified).

ENDURANCE AND DATA RETENTION

PARAMETER	MIN	UNITS
Minimum Endurance	100,000	Data Changes per Bit per Register
Data Retention	100	Years

CAPACITANCE

SYMBOL	TEST	ТҮР	UNITS	TEST CONDITIONS
C _{OUT} (Note 5)	Output Capacitance (SO)	8	pF	V _{OUT} = 0V
C _{IN} (Note 5)	Input Capacitance (A0, SI, and SCK)	6	pF	$V_{IN} = 0V$

POWER-UP TIMING

SYMBOL	PARAMETER	MIN	MAX	UNITS
t _R V _{CC} (Note 5)	V _{CC} Power-up Ramp	0.2	50	V/msec

NOTES:

1. Absolute Linearity is utilized to determine actual wiper voltage versus expected voltage as determined by wiper position when used as a potentiometer.

2. Relative Linearity is utilized to determine the actual change in voltage between two successive tap positions when used as a potentiometer. It is a measure of the error in step size.

- 3. MI = RTOT/63 or $(V_H V_L)/63$, single pot
- 4. Typical = Individual array resolution.
- 5. Parameters with MIN and/or MAX limits are 100% tested at +25°C, unless otherwise specified. Temperature limits established by characterization and are not production tested.
- 6. Limits should be considered typical and are not production tested.
- 7. This parameter is not production tested. Parameter established by characterization.

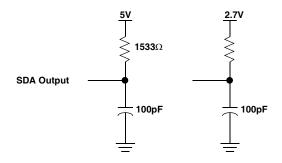
Power-up Requirements

(Power-up sequencing can affect correct recall of the wiper registers) The preferred power-on sequence is as follows: First V_{CC} and then the potentiometer pins, R_H, R_L, and R_W. Voltage should not be applied to the potentiometer pins before V_{CC} is applied. The V_{CC} ramp rate specification should be met, and any glitches or slope changes in the V_{CC} line should be held to <100mV if possible. Also, V_{CC} should not reverse polarity by more than 0.5V. Recall of wiper position will not be complete until V_{CC} reaches its final value.

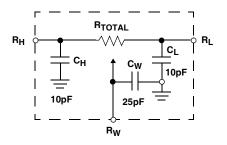
AC Test Conditions

Input pulse levels	V _{CC} x 0.1 to V _{CC} x 0.9
Input rise and fall times	10ns
Input and output timing level	V _{CC} x 0.5

Equivalent AC Load Circuit



Circuit #3 SPICE Macro Model



AC Timing

SYMBOL	PARAMETER	MIN (Note 5)	TYP (Note 6)	MAX (Note 5)	UNITS
fsck	SSI/SPI Clock Frequency			2.0	MHz
tCYC	SSI/SPI Clock Cycle Time	500			ns
t _{WH}	SSI/SPI Clock High Time	200			ns
t _{WL}	SSI/SPI Clock Low Time	200			ns
t _{LEAD}	Lead Time	250			ns
t _{LAG}	Lag Time	250			ns
t _{SU}	SI, SCK, HOLD and CS Input Setup Time	50			ns
t _H	SI, SCK, HOLD and CS Input Hold Time	50			ns
t _{RI} ⁽⁷⁾	SI, SCK, HOLD and CS Input Rise Time			2	μs
t _{FI} ⁽⁷⁾	SI, SCK, HOLD and CS Input Fall Time			2	μs
t _{DIS}	SO Output Disable Time	0		500	ns
t _V	SO Output Valid Time			150	ns
^t HO	SO Output Hold Time	0			ns
^t RO	SO Output Rise Time		50		ns
^t FO	SO Output Fall Time		50		ns
^t HOLD	HOLD Time	400			ns
tHSU	HOLD Setup Time	100			ns
t _{HH}	HOLD Hold Time	100			ns
t _{HZ}	HOLD Low to Output in High Z		100		ns
t _{LZ}	HOLD High to Output in Low Z		100		ns
т _I	Noise Suppression Time Constant at SI, SCK, \overline{HOLD} and \overline{CS} inputs		20		ns
t _{CS}	CS Deselect Time	2			μs
twpasu	WP, A0 and A1 Setup Time	0			ns
twpah	WP, A0 and A1 Hold Time	0			ns

High-Voltage Write Cycle Timing

SYMBOL	PARAMETER	TYP (NOTE 6)	MAX (NOTE 5)	UNITS
t _{WR}	High-voltage Write Cycle Time (Store Instructions)	5	10	ms

XDCP Timing

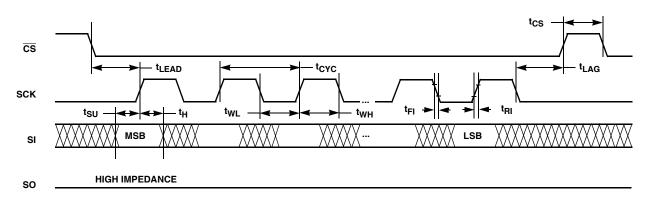
SYMBOL	PARAMETER	MIN (NOTE 5)	MAX (NOTE 5)	UNITS
t _{WRPO}	Wiper Response Time After The Power Supply Is Stable		10	μs
tWRL	Wiper Response Time After Instruction Issued (All Load Instructions)		10	μs
^t WRID	Wiper Response Time From An Active SCL/SCK Edge (Increment/Decrement Instruction)		10	μs

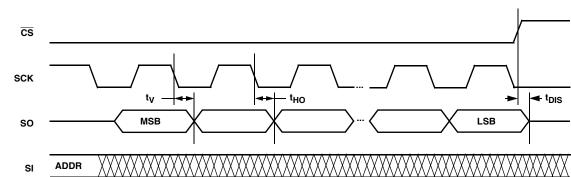
Symbol Table

WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM LOW TO HIGH	
	MAY CHANGE FROM HIGH TO LOW	
	DON'T CARE: CHANGES ALLOWED	CHANGING: STATE NOT KNOWN
	N/A	CENTER LINE IS HIGH IMPEDANCE

Timing Diagrams

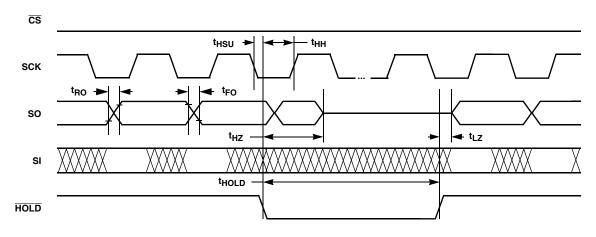
Input Timing



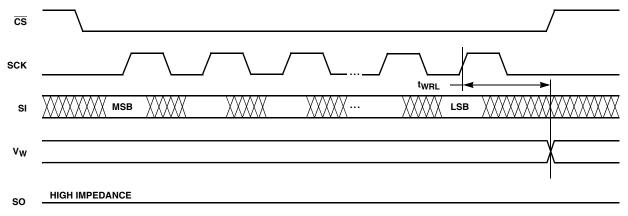


Output Timing

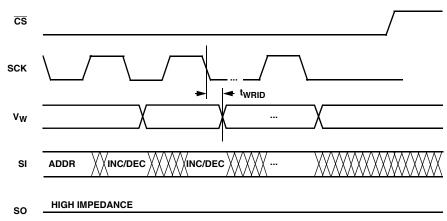
Hold Timing



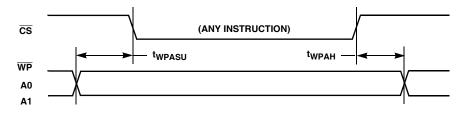
XDCP Timing (for All Load Instructions)



XDCP Timing (for Increment/Decrement Instruction)



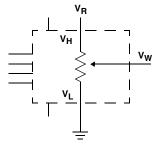
Write Protect and Device Address Pins Timing



Applications information

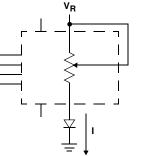
1. Electronic potentiometers provide three powerful application advantages: The variability and reliability of a solid-state potentiometer,

Basic Configurations of Electronic Potentiometers



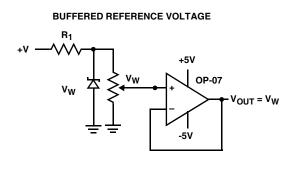
THREE TERMINAL POTENTIOMETER; VARIABLE VOLTAGE DIVIDER

- 2. The flexibility of computer-based digital controls)
- 3. the retentivity of nonvolatile memory used for the storage of multiple potentiometer settings or data.



TWO TERMINAL VARIABLE RESISTOR; VARIABLE CURRENT

Application Circuits



CASCADING TECHNIQUES

vw

ьV

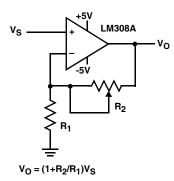
(a)

÷۷

٧w

(b)

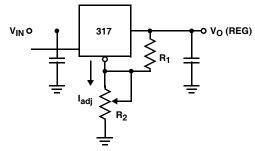
NONINVERTING AMPLIFIER



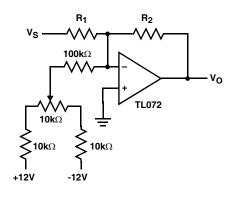
VOLTAGE REGULATOR

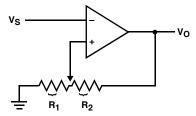






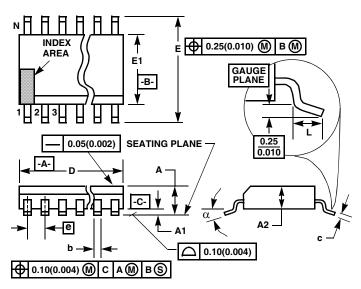
 V_{O} (REG) = 1.25V (1+R₂/R₁)+I_{adj} R₂





 $V_{UL} = {R_1/CR_1+R_2} V_O(max)$ $V_{LL} = {R_1/CR_1+R_2} V_O(min)$

Thin Shrink Small Outline Plastic Packages (TSSOP)



NOTES:

- 1. These package dimensions are within allowable dimensions of JEDEC MO-153-AC, Issue E.
- 2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
- 4. Dimension "E1" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.15mm (0.006 inch) per side.
- 5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- 6. "L" is the length of terminal for soldering to a substrate.
- 7. "N" is the number of terminal positions.
- 8. Terminal numbers are shown for reference only.
- 9. Dimension "b" does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm (0.003 inch) total in excess of "b" dimension at maximum material condition. Minimum space between protrusion and adjacent lead is 0.07mm (0.0027 inch).
- 10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact. (Angles in degrees)

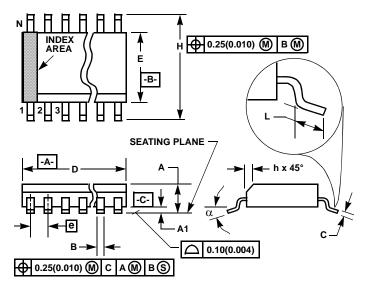
M14.173

14 LEAD THIN SHRINK SMALL OUTLINE PLASTIC PACKAGE

	INCHES		MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
А	-	0.047	-	1.20	-
A1	0.002	0.006	0.05	0.15	-
A2	0.031	0.041	0.80	1.05	-
b	0.0075	0.0118	0.19	0.30	9
С	0.0035	0.0079	0.09	0.20	-
D	0.195	0.199	4.95	5.05	3
E1	0.169	0.177	4.30	4.50	4
е	0.026 BSC		0.65 BSC		-
E	0.246	0.256	6.25	6.50	-
L	0.0177	0.0295	0.45	0.75	6
Ν	14		14		7
α	0 ⁰	8 ⁰	0 ⁰	8 ⁰	-

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Small Outline Plastic Packages (SOIC)



NOTES:

- 1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- 2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
- 4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
- 5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- 6. "L" is the length of terminal for soldering to a substrate.
- 7. "N" is the number of terminal positions.
- 8. Terminal numbers are shown for reference only.
- 9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch)
- 10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

M16.3 (JEDEC MS-013-AA ISSUE C) 16 LEAD WIDE BODY SMALL OUTLINE PLASTIC PACKAGE

	INC	HES	MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
А	0.0926	0.1043	2.35	2.65	-
A1	0.0040	0.0118	0.10	0.30	-
В	0.013	0.0200	0.33	0.51	9
С	0.0091	0.0125	0.23	0.32	-
D	0.3977	0.4133	10.10	10.50	3
Е	0.2914	0.2992	7.40	7.60	4
е	0.050 BSC		1.27 BSC		-
Н	0.394	0.419	10.00	10.65	-
h	0.010	0.029	0.25	0.75	5
L	0.016	0.050	0.40	1.27	6
Ν	16		16		7
α	0°	8°	0°	8°	-

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